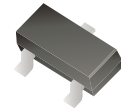


# CMSP1013V3-HF

**P-Channel**  
**RoHS Device**  
**Halogen Free**



$V_{(BR)DSS}$	$R_{DS(on) Typ}$	$I_D$
-20V	0.64Ω @ -4.5V	-540mA
	1.1Ω @ -2.5V	
	1.9Ω @ -1.8V	

## Features

- Very low level gate drive requirements allowing direct operation in 3V circuits.  $V_{GS(th)} < 1.2V$ .
- Compact industrial standard SOT-323 surface mount package.
- ESD protected gate.
- Pb-free lead plating and halogen-free package.

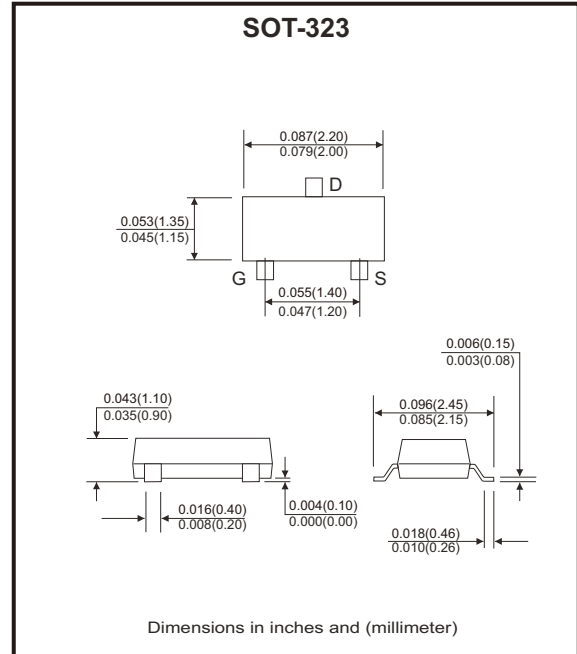
## Mechanical data

- Case: SOT-323, molded plastic.
- Mounting position: Any.

## Maximum Ratings (at TA=25°C unless otherwise noted)

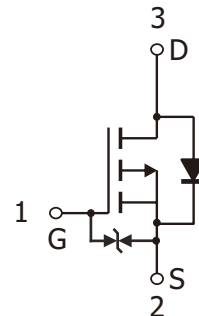
Parameter	Symbol	Limits	Unit
Drain-source voltage	$V_{DS}$	-20	V
Gate-source voltage	$V_{GS}$	±10	V
Continuous drain current @ $T_A=25^\circ C, V_{GS}=4.5V$	$I_D$	-0.54	A
Pulsed drain current (Note 1)	$I_{DM}$	-1.5	
Maximum power dissipation @ $T_A=25^\circ C$ (Note 2)	$P_D$	350	mW
Thermal resistance, junction-to-ambient	$R_{thja}$	357	°C/W
Operating junction and storage temperature	$T_j, T_{STG}$	-55 ~ +150	°C

Notes: 1. Pulse width ≤ 10μs, duty cycle ≤ 2%.  
2. Surface mounted on 1 in<sup>2</sup> copper pad of FR-4 board, t ≤ 5s.



## Circuit Diagram

- 1 G : Gate
- 2 S : Source
- 3 D : Drain



## Electrical Characteristics (at TA=25°C unless otherwise noted)

Symbol	Min	Typ	Max	Unit	Test Conditions
<b>Static</b>					
BV <sub>DSS</sub>	-20			V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA
V <sub>GS(th)</sub>	-0.5	-0.8	-1.2	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA
GFS		0.5		S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -200mA
I <sub>GSS</sub>			±10	μA	V <sub>GS</sub> = ±10V, V <sub>DS</sub> = 0V
I <sub>DSS</sub>			-1		V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V
			-10		V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 55°C
*R <sub>DS(on)</sub>		0.64	0.9	Ω	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -430mA
		0.68	0.9		V <sub>GS</sub> = -4V, I <sub>D</sub> = -300mA
		1.1	1.4		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -300mA
		1.9	2.7		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -150mA
<b>Dynamic</b>					
C <sub>iss</sub>		59		pF	V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V, f = 1MHz
C <sub>oss</sub>		21			
C <sub>rss</sub>		15			
*t <sub>d(ON)</sub>		5		ns	V <sub>DS</sub> = -6V, I <sub>D</sub> = -500mA, V <sub>GS</sub> = -4.5V, R <sub>G</sub> = 50Ω
*t <sub>r</sub>		6			
*t <sub>d(OFF)</sub>		42			
*t <sub>f</sub>		14			
*Q <sub>g</sub>		1.2		nC	V <sub>DS</sub> = -5V, I <sub>D</sub> = -250mA, V <sub>GS</sub> = -4.5V
*Q <sub>gs</sub>		0.38			
*Q <sub>gd</sub>		0.23			
<b>Source-Drain Diode</b>					
*I <sub>S</sub>			-0.54	A	
*I <sub>SM</sub>			-1.5		
*V <sub>SD</sub>		-0.77	-1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -100mA

\* Pulse test: Pulse width ≤ 300μs, duty cycle ≤ 2%.

## Typical Characteristic (CMSP1013V3-HF)

Fig.1 - Typical Output Characteristics

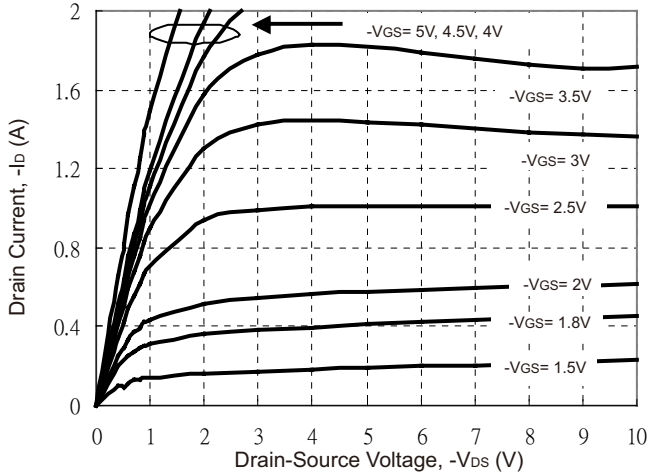


Fig.2 - Breakdown Voltage vs Ambient Temperature

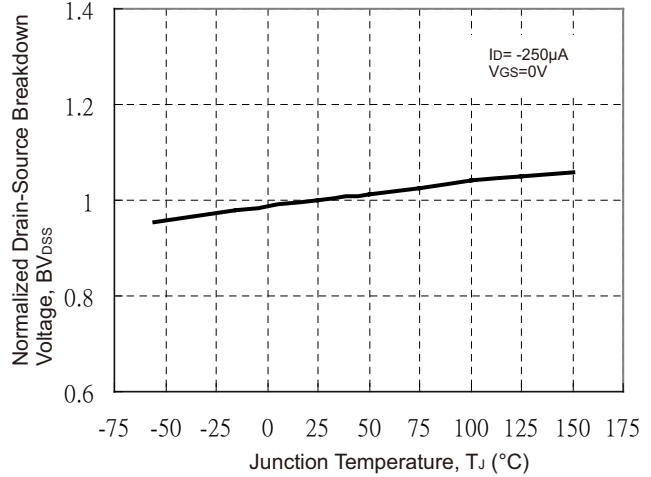


Fig.3 - Static Drain-Source On-State Resistance vs Drain Current

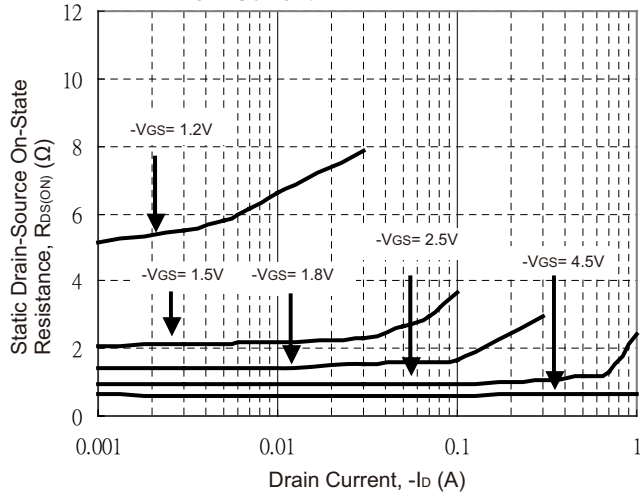


Fig.4 - Reverse Drain Current vs Source-Drain Voltage

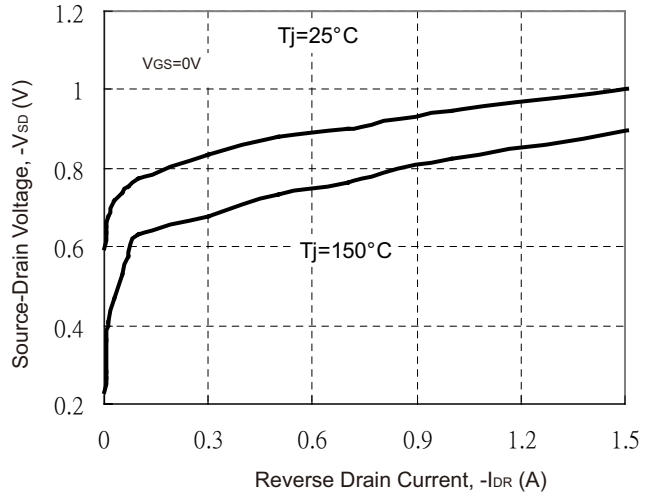


Fig.5 - Static Drain-Source On-State Resistance vs Gate-Source Voltage

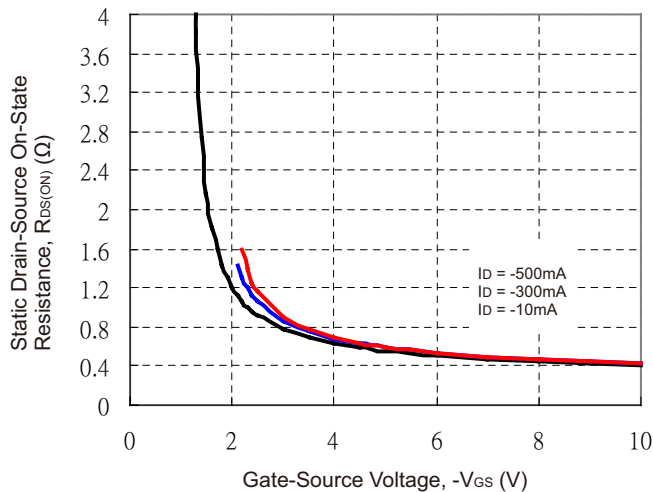
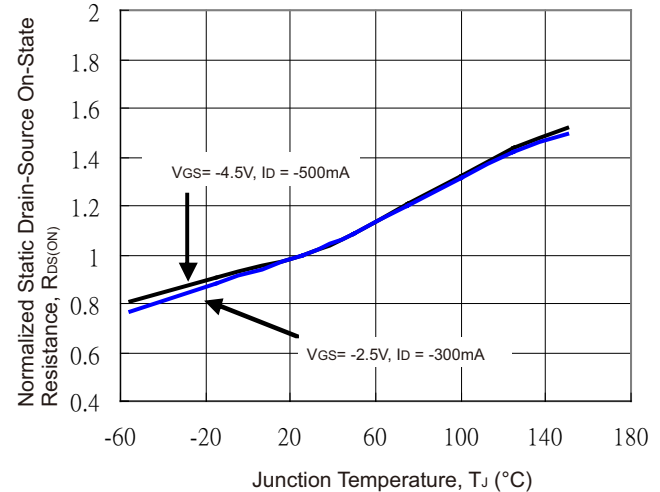


Fig.6 - Drain-Source On-State Resistance vs Junction Temperature



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## Typical Characteristic (CMSP1013V3-HF)

Fig.7 - Capacitance vs Drain-to-Source Voltage

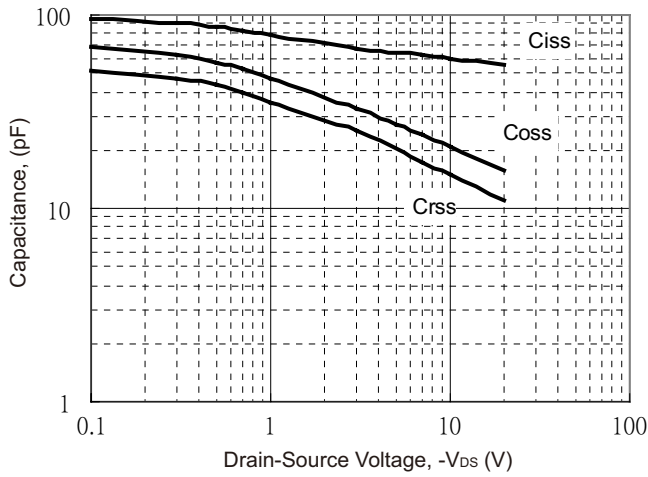


Fig.8 - Threshold Voltage vs Junction Temperature

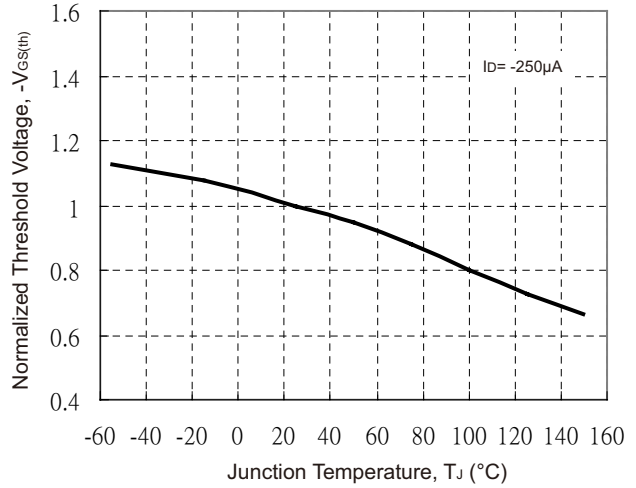


Fig.9 - Single Pulse Power Rating, Junction to Ambient

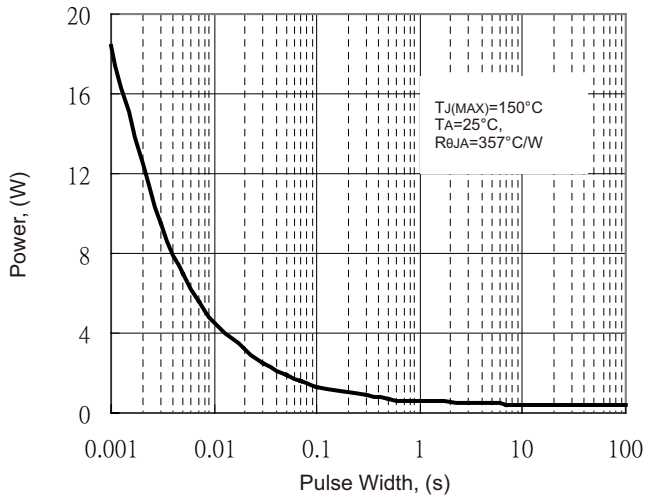


Fig.10 - Gate Charge Characteristics

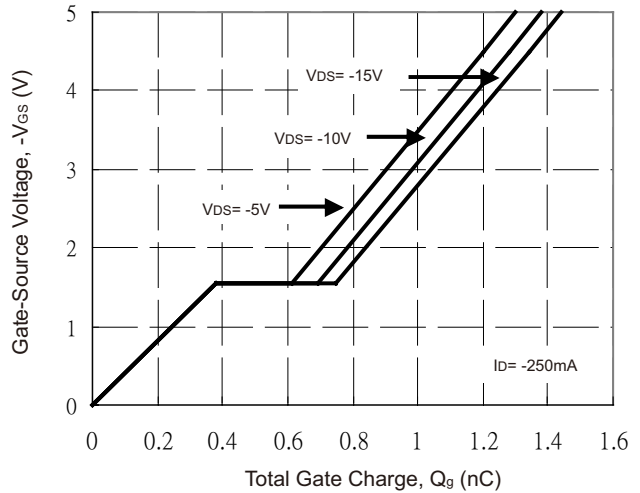


Fig.11 - Maximum Safe Operating Area

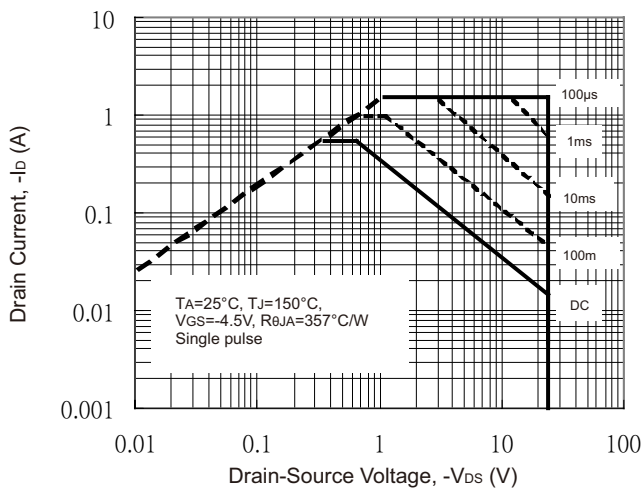
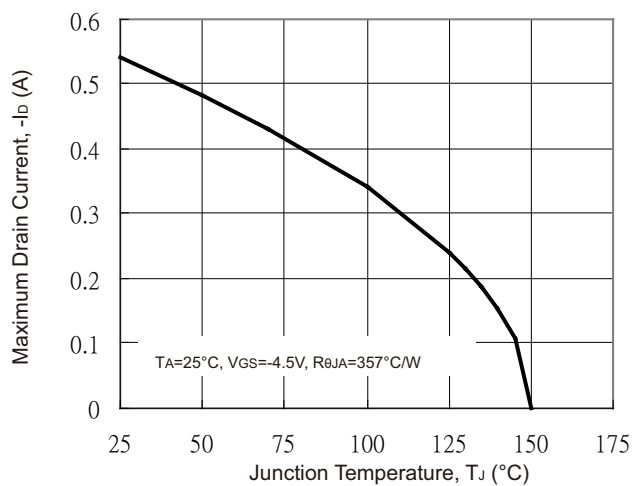


Fig.12 - Maximum Drain Current vs Junction Temperature



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REV:B

## Typical Characteristic (CMSP1013V3-HF)

Fig.13 - Typical Transfer Characteristics

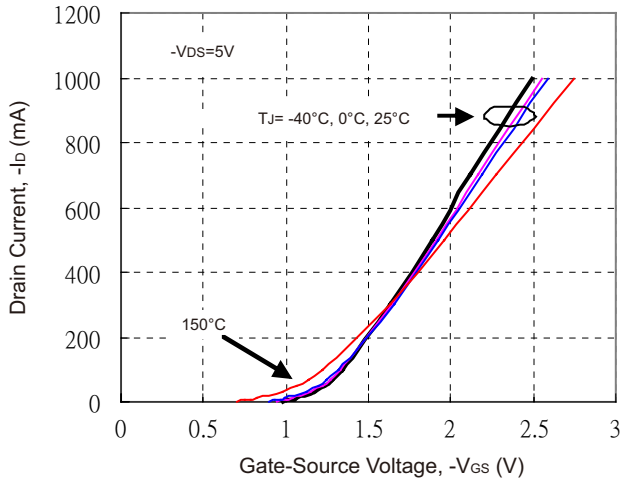


Fig.14 - Power Derating Curve

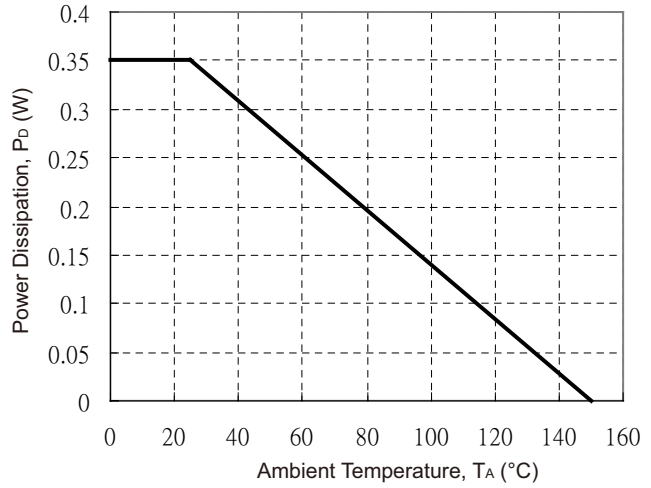
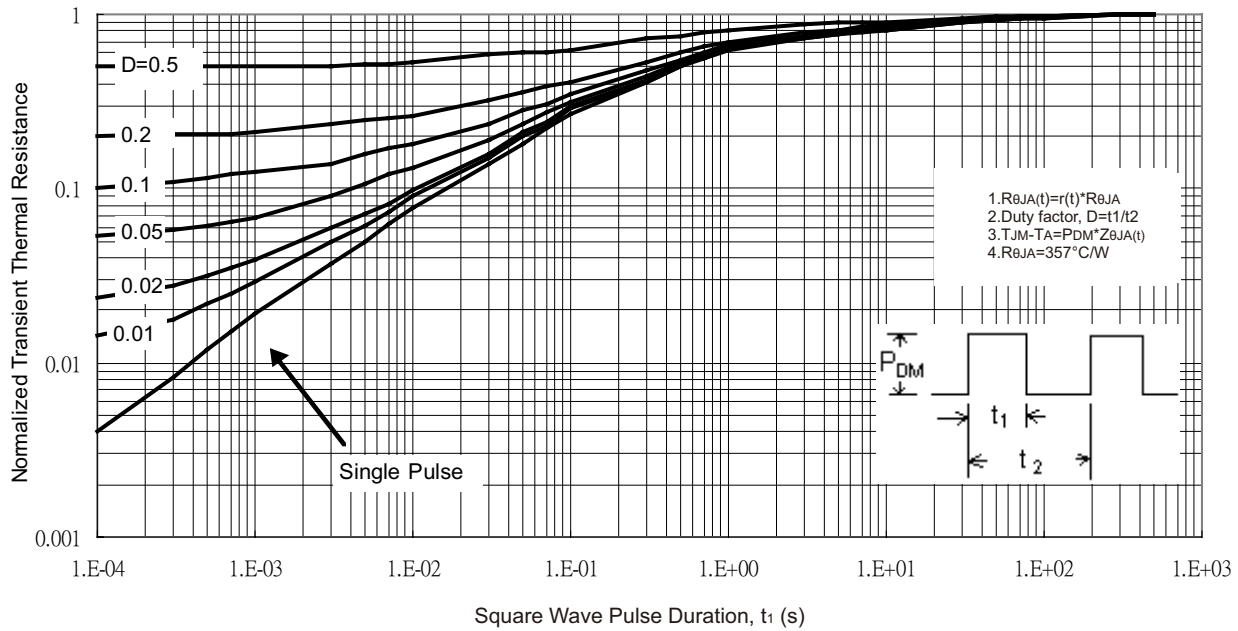
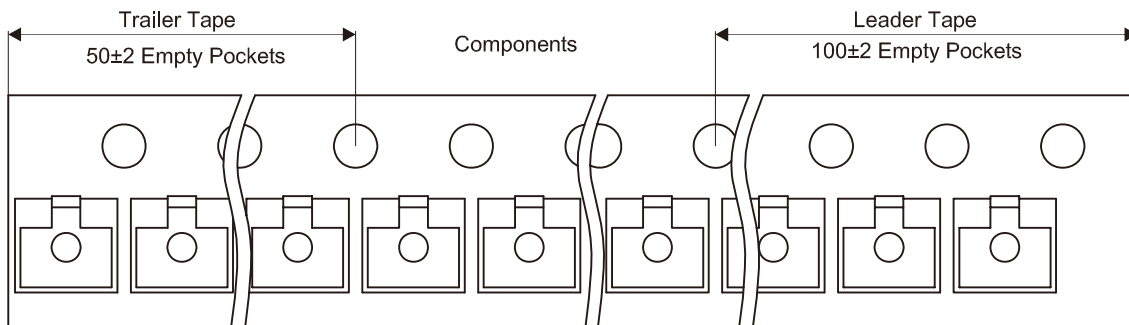
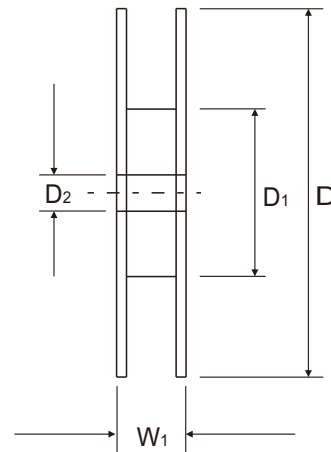
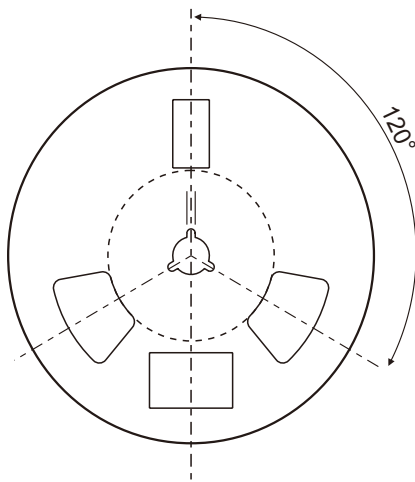
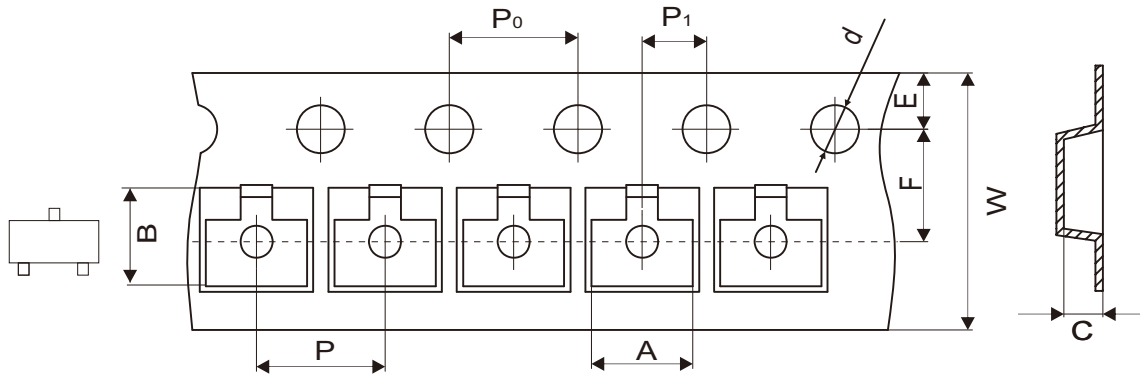


Fig.15 - Transient Thermal Response Curves



Reel Taping Specification



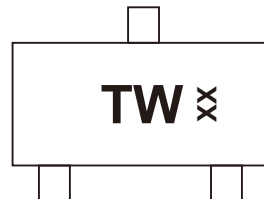
SOT-323	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	2.25 ± 0.05	2.55 ± 0.05	1.19 ± 0.05	1.55 ± 0.10	178.00 ± 2.00	54.40 ± 1.00	13.00 ± 1.00
	(inch)	0.089 ± 0.002	0.100 ± 0.002	0.047 ± 0.002	0.061 ± 0.004	7.008 ± 0.079	2.142 ± 0.039	0.512 ± 0.039

SOT-323	SYMBOL	E	F	P	P0	P1	W	W1
	(mm)	1.75 ± 0.10	3.50 ± 0.10	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.10	8.00 + 0.30/-0.10	12.30 ± 1.00
	(inch)	0.069 ± 0.004	0.138 ± 0.004	0.157 ± 0.004	0.157 ± 0.004	0.079 ± 0.004	0.315 + 0.012/-0.004	0.484 ± 0.039

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## Marking Code

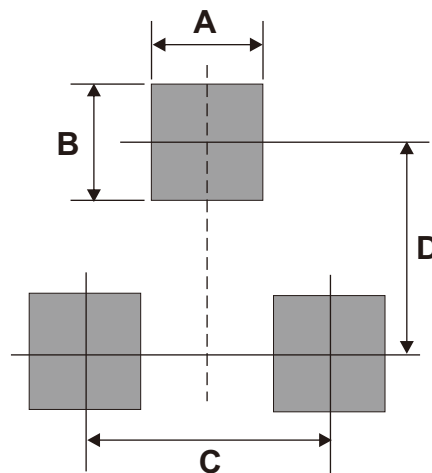
Part Number	Marking Code
CMSP1013V3-HF	TW



XX = Control code

## Suggested P.C.B. PAD Layout

SIZE	SOT-323	
	(mm)	(inch)
A	0.50	0.020
B	0.80	0.031
C	1.30	0.012
D	2.20	0.087



## Standard Packaging

Case Type	REEL PACK	
	REEL ( pcs )	Reel Size (inch)
SOT-323	3,000	7